# **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)TYP</sub>	l <sub>D</sub>
135V	3.0mΩ@10V	270A



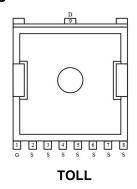
#### **Feature**

- Fast Switching
- Low Gate Charge and Rdson
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

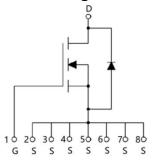
# **Applications**

- PWM Application
- Hard switched and high frequency circuits
- Power Management

#### **Package**



#### Circuit diagram



# Marking



SP013N03GHTO : Device Code
\*\* : Week Code

#### **Order Information**

Device	Package	Unit/Tape
SP013N03GHTO	TOLL	2000

135V N-Channel Power MOSFET

# Absolute maximum ratings (Ta=25°C,unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V <sub>DS</sub>	135	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current(Tc=25℃)	ΙD	270	A
Continuous Drain Current(Tc=100℃)	I <sub>D</sub>	180	А
Pulsed Drain Current	I <sub>DM</sub>	1080	А
Single Pulse Avalanche Energy <sup>1</sup>	Eas	1386	mJ
Power Dissipation(Tc=25℃)	P <sub>D</sub>	196	W
Thermal Resistance Junction-to-Case	R <sub>eJC</sub>	0.32	°C/W
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	℃
Operating Junction Temperature Range	TJ	-55 to 150	℃

#### Electrical characteristics (Ta=25°C, unless otherwise noted)

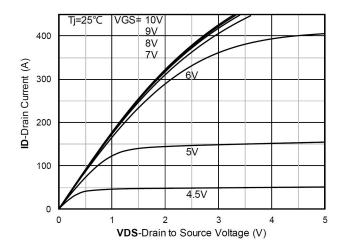
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	ID = 250μA, VGS = 0V	135	150	-	٧
Drain-Source Leakage Current	I <sub>DSS</sub>	VDS =108V, VGS = 0V	-	-	1	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	VGS = ±20V, VDS = 0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	VDS = VGS, ID = 250µA	2	3	4	V
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	VGS = 10V, ID = 20A	-	3.0	3.8	mΩ
Dynamic characteristics					•	
Input Capacitance	Ciss		-	9023	-	
Output Capacitance	Coss	VDS=75V , VGS=0V , f=1MHz		587	-	pF
Reverse Transfer Capacitance	Crss			23	-	
Total Gate Charge	Qg	VDS=75V , VGS=10V , ID=20A	-	89	-	
Gate-Source Charge	Q <sub>gs</sub>		-	43	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	1		28	-	
Switching Characteristics						
Turn-On Delay Time	T <sub>d(on)</sub>		-	26	-	
Rise Time	Tr	VDD=75V, VGS=10V , RG=3.0Ω, ID=20A	-	39	-	
Turn-Off Delay Time	T <sub>d(off)</sub>		-	54	-	nS
Fall Time	T <sub>f</sub>			21	-	1
Diode Characteristics						
Diode Forward Voltage	V <sub>SD</sub>	VGS=0V , I <sub>S</sub> =1A , TJ=25℃	-	-	1.2	V
Maximum Body-Diode Continuous Current	Is		-	-	270	Α
Reverse Recovery Time	Trr	I <sub>S</sub> =140A, di/dt=100A/us, TJ=25℃		175	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>			544	_	nC

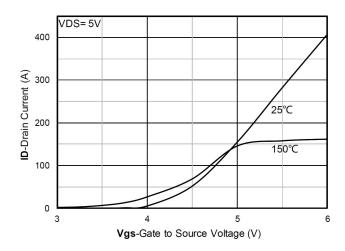
#### Note:

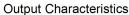
1. The test condition is VDD=50V,VGS=10V,L=0.5mH,RG=25 $\Omega$ 

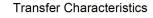


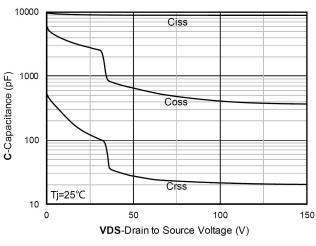
# **Typical Characteristics**

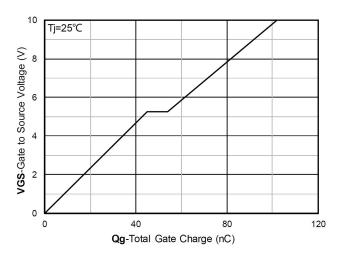






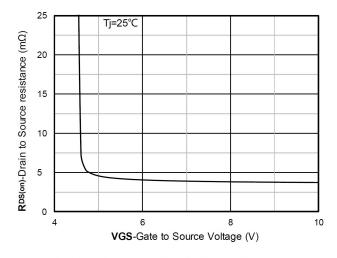


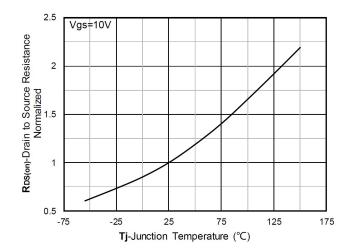




Capacitance Characteristics

Gate Charge

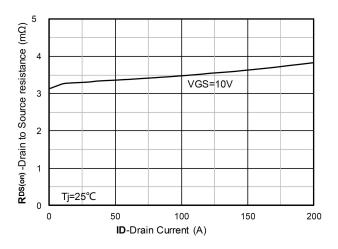


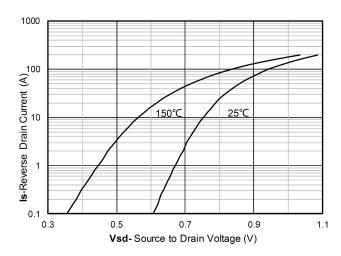


On-Resistance vs Gate to Source Voltage

Normalized On-Resistance

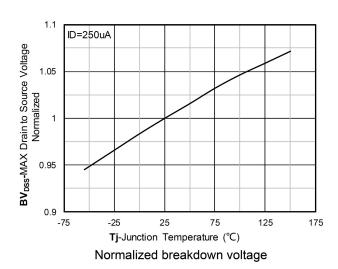


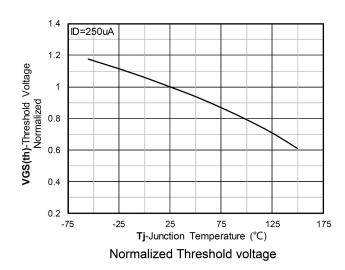


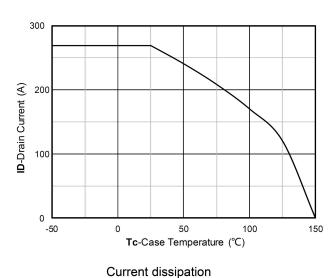


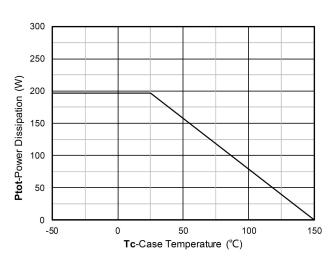
RDS(on) VS Drain Current

Forward characteristics of reverse diode



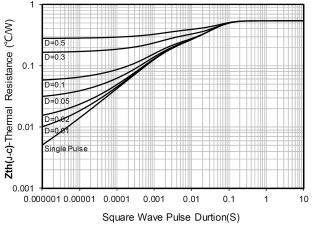




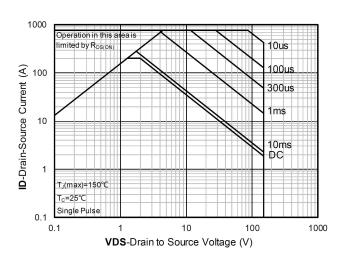


Power dissipation

# Siliup Semiconductor

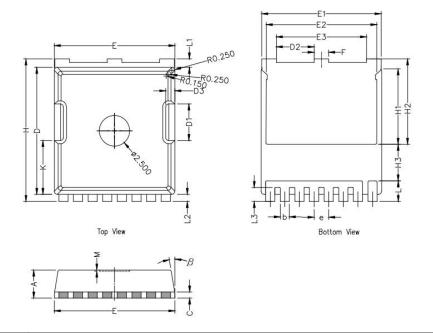


Maximum Transient Thermal Impedance



Safe Operation Area

# TOLL Package Information



Symbol	Dimensions In Millimeters				
	Min.	Nom.	Max.		
Α	2.20	2.30	2.40		
b	0.65	0.75	0.85		
С		0.508 REF			
D	10.25	10.40	10.55		
D1	2.85	3.00	3.15		
E	9.75	9.90	10.05		
E1	9.65	9.80	9.95		
E2	8.95	9.10	9.25		
E3	7.25	7.40	7.55		
е	1.20 BSC				
F	1.05	1.20	1.35		
Н	11.55	11.70	11.85		
H1	6.03	6.18	6.33		
H2	6.85	7.00	7.15		
H3		3.00 BSC			
L	1.55	1.70	1.85		
L1	0.55	0.7	0.85		
L2	0.45	0.6	0.75		
М	0.08 REF.				
β	8°	10°	12°		
K	4.25	4.40	4.55		